



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC057N03MS G		<b>Issued</b>		5. February 2015	
<b>MA#</b>				MA001321670					
<b>Package</b>				PG-TDSON-8-14		<b>Weight*</b>		105.63 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.076	1.02	1.02	10191	10191	
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		92		
	non noble metal	zinc	7440-66-6	0.039	0.04		368		
	non noble metal	iron	7439-89-6	0.778	0.74		7365		
wire	non noble metal	copper	7440-50-8	31.590	29.91	30.70	299062	306887	
	non noble metal	copper	7440-50-8	0.058	0.05	0.05	546	546	
	encapsulation	organic material	carbon black	1333-86-4	0.258	0.24		2446	
plastics	plastics	epoxy resin	-	8.010	7.58		75829		
	inorganic material	silicondioxide	60676-86-0	43.408	41.10	48.92	410947	489222	
	leadfinish	non noble metal	tin	7440-31-5	1.243	1.18	1.18	11763	11763
plating	noble metal	silver	7440-22-4	0.037	0.04	0.04	354	354	
solder	noble metal	silver	7440-22-4	0.033	0.03		310		
	non noble metal	tin	7440-31-5	0.026	0.02		248		
	non noble metal	lead	7439-92-1	1.250	1.18	1.23	11832	12390	
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.01		51		
	non noble metal	zinc	7440-66-6	0.021	0.02		202		
	non noble metal	iron	7439-89-6	0.428	0.40		4048		
	non noble metal	copper	7440-50-8	17.360	16.43	16.86	164346	168647	
*deviation	< 10%					Sum in total:	100.00	1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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